

DATA SHEET

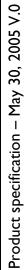
LOW OHMIC HIGH POWER CHIP RESISTORS

RL-High power series (Pb Free)

5%, 1%

sizes 0805/1206







YAGEO



Chip Resistor Surface Mount

RL-High power

SERIES

0805/1206 (Pb Free)

SCOPE

This specification describes RL0805/1206 low ohmic high power chip resistors with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO ORDERING CODE

CTC CODE

RL XXXX X X X XX XXXX L

(1) (2) (3) (4) (5)(6) (7)

(I) SIZE

0805

1206

(2) TOLERANCE

 $F = \pm 1\%$ $J = \pm 5\%$

(3) PACKAGING TYPE

R = Paper/PE taping reel

(4) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(5) TAPING REEL

7 = 7 inch dia. Reel

(6) POWER RATING

 $W = 2 \times standard power^{(d)}$

(7) RESISTANCE VALUE

0R01, 0R056, 0R56, 0R91 of E24 series (E48/96 on request).

(8) RESISTOR TERMINATIONS

L = Lead free terminations (matte tin) (a)

ORDERING EXAMPLE

The ordering code of a RL0805 chip resistor, value 0.56 Ω , 1/4 W with ±1% tolerance, supplied in 7-inch tape reel is: RL0805FR-7W0R56RL.

NOTE

- The "L" at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp "LFP"= lead free production.
- Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- Products with lead in terminations will be phased out in the coming months (before July 1st, 2006).
- d. Standard power for size 0805 is 1/8 Watt, and size1206 is 1/4 Watt.





0805/1206 (Pb Free)

MARKING

RL0805 / RL1206, R = $10/20/30/40/50/60 \text{ m}\Omega$



E-24 series: 4 digits

The "R" is used as a decimal point; the other 3 digits are significant.

SPECIALITY EXCEPT 10/20/30/40/50/60 mΩ



No marking

Fig. 2 Value = 22 m Ω

For marking codes, please see EIA-marking code rules in data sheet "Chip resistors marking".

CONSTRUCTION

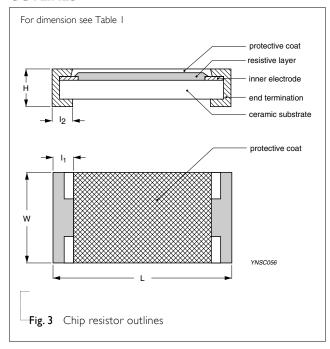
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the resistance value. Finally, the two external terminations (matte tin) are added. See fig. 3.

DIMENSION

Table I For outlines see fig. 3

TYPE	L (mm)	W (mm)	H (mm)	I _I (mm)	I ₂ (mm)
RL0805	2.00 ±0.10	1.25 ±0.10	0.50 ±0.10	0.35 ±0.20	0.35 ±0.20
RL1206	3.10 ±0.10	1.60 ±0.10	0.55 ±0.10	0.45 ±0.20	0.40 ±0.20

OUTLINES



ELECTRICAL CHARACTERISTICS

Table 2

TYPE / RESISTANCE RANGE	TEMPERATURE COEFFICIENT OF RESISTANCE					
	I0mΩ≤R≤I8mΩ	I8mΩ <r≤47mω< th=""><th>47mΩ<r≤91mω< th=""><th>91mΩ<r≤360mω< th=""><th>360mΩ<r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<></th></r≤360mω<></th></r≤91mω<></th></r≤47mω<>	47mΩ <r≤91mω< th=""><th>91mΩ<r≤360mω< th=""><th>360mΩ<r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<></th></r≤360mω<></th></r≤91mω<>	91mΩ <r≤360mω< th=""><th>360mΩ<r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<></th></r≤360mω<>	360mΩ <r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<>	500mΩ <r<iω< th=""></r<iω<>
RL0805	±1,500 ppm/°C	±1,200 ppm/°C	±1,000 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C
$\overline{RL1206}$ $10m\Omega \leq R < 1\Omega$	±1,500 ppm/°C	±1,200 ppm/°C	±1,000 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data" conformed to EU RoHS.

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PACKING STYLE	REEL DIMENSION	RL0805	RL1206
Paper/PE taping reel (R)	7" (178 mm)	5,000	5,000

NOTE

1. For Paper/PE/Embossed tape and reel specification/dimensions, please see the special data sheet "Packing" document.

FUNCTIONAL DESCRIPTION

OPERATINGTEMPERATURE RANGE

Range: -55°C to +125°C

POWER RATING

Each type rated power at 70°C: RL0805=1/4 W; RL1206=1/2 W.

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

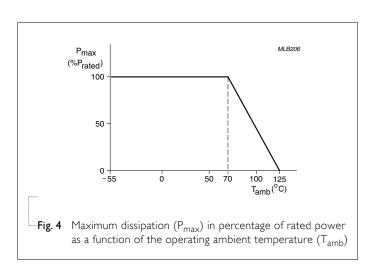
$$V = \sqrt{(P \times R)}$$

Where

V = Continuous rated DC or AC (rms) working voltage (V)

P = Rated power (W)

 $R = Resistance value (\Omega)$





TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Temperature Coefficient of	MIL-STD-202F-method 304; JIS C 5202-4.8	At +25/–55 °C and +25/+125 °C Refer to table 2		
Resistance	JIS C 3202-4.0	Formula:		
(T.C.R.)		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$		
		Where t_1 =+25 °C or specified room temperature		
		t_2 =-55 °C or +125 °C test temperature		
		R_1 =resistance at reference temperature in ohms		
		R ₂ =resistance at test temperature in ohms		
Thermal Shock	MIL-STD-202F-method 107G; IEC 60115-1 4.19	At -65 (+0/-10) °C for 2 minutes and at +125 (+10/-0) °C for 2 minutes; 25 cycles	±1.0%	
Low	MIL-R-55342D-Para 4.7.4	At –65 (+0/–5) °C for I hour, RCWV applied	±1.0%	
Temperature Operation		for 45 (+5/–0) minutes	No visible damage	
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room temperature	±1.0% for 1% tol.	
Overload	IEC 60115-1 4.13		±2.0% for 5% tol.	
			No visible damage	
Insulation	MIL-STD-202F-method 302;	One DC voltage (V) applied for 1 minute	≥10 GΩ	
Resistance	IEC 60115-1 4.6.1.1	Details see below table 5		
Dielectric	MIL-STD-202F-method 301;	One AC voltage (V _{ms}) applied for 1 minute	No breakdown or flashover	
Withstand Voltage	IEC 60115-1 4.6.1.1	Details see below table 5		
Resistance to Soldering Heat	MIL-STD-202F-method 210C;	Unmounted chips; 260 ±5 °C for 10 ±1	±1.0%	
	IEC 60115-1 4.18	seconds	No visible damage	
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	±2% for 1% tol.	
	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	±3% for 5% tol.	



Chip Resistor Surface Mount RL-High power SERIES 0805/1206 (Pb Free)

Table 4 Test condition, procedure and requirements (continued)

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% covered)
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage
Resistance to	MIL-STD-202F-method 215;	Isopropylalcohol (C ₃ H ₇ OH) or dichloromethane	No smeared
Solvent	IEC 60115-1 4.29	(CH ₂ Cl ₂) followed by brushing	
Humidity	JIS C 5202 7.5;	I,000 hours; 40±2 °C; 93(+2/-3)% RH	+2.0%
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	
Leaching	EIA/IS 4.13B;	Solder bath at 260±5 °C	No visible damage
	IEC 60115-8 4.18	Dipping time: 30±1 seconds	

Table 5 Criteria of rated continued working voltage and overload voltage

TYPE	RL0805	RL1206
Voltage (DC/unit: V) / (AC/ unit: V _{rms})	300	500



Product specification

Chip Resistor Surface Mount RL-High power SERIES 0805/1206 (Pb Free)

REVISION HISTORY

REVISION DATE CHANGE NOTIFICATION DESCRIPTION

Version 0 May 30, 2005 - First issue of this specification

